Organizational Chart

Europe | Japan | North America | China | Korea | Taiwan

Last Updated: January 2020
v1
Global Technical Committee (GTC) and Technical Committee (TC) Chapters
<table>
<thead>
<tr>
<th>Global Technical Committee</th>
<th>Locale</th>
<th>China</th>
<th>Europe</th>
<th>Japan</th>
<th>Korea</th>
<th>North America</th>
<th>Taiwan</th>
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<tbody>
<tr>
<td>EH&amp;S</td>
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Legend:
- **TCC** – The Locale has a TC Chapter of the global technical committees
- **CFG** – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committees

Note 1: An underlined **Locale** has an RSC and may also be referred as a “Region” (e.g., “Europe Region”)
Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)
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<tr>
<td>Micropatterning (Microlithography*)</td>
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*In NA, Micropatterning is traditionally called Microlithography
**3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017
Regional Standards Committee (RSC) Organizations
# SEMI Europe RSC Organization

**Co-Chairs:** Bert Planting – ASML, Werner Bergholz – International Standards Consulting  
**Vice-Chair:** Frank Petzold – Trustsec

<table>
<thead>
<tr>
<th>Europe Chapter of Automation Technology</th>
<th>Europe Chapter of Liquid Chemicals</th>
<th>Europe Chapter of Physical Interfaces &amp; Carriers</th>
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<tbody>
<tr>
<td>Global Technical Committee</td>
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<tr>
<td>C: Christian Hoffmann – PEER Group</td>
<td>C: Jochen Ruth – Pall Corporation</td>
<td>C: Frank Petzold – Trustsec</td>
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<th>Europe Chapter of Compound Semiconductor Materials</th>
<th>Europe Chapter of Information &amp; Control</th>
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<td>C: Arnd Weber – SiCrystal</td>
<td>C: Frank Petzold – Trustsec</td>
<td>C: Peter Wagner – Consultant</td>
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<th>Europe Chapter of Metrics</th>
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<tr>
<td>Global Technical Committee</td>
<td>C: Fritz Passek - Siltronic</td>
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Japan Chapter of 3D Packaging & Integration Global Technical Committee
C: Masahiro Tsuriya – INEMI
C: Haruo Shimamoto – AIST
C: Kazunori Kato – AIT

Japan Chapter of Automation Technology Global Technical Committee
C: Terry Asakawa – Vistaideal Consulting
C: Teruaki Ito – Mitsubishi Electric
C: Fumiyasu Obuchi – SIEMENS
C: Yasuhiro Kaneko – YAMAHA Motor

Japan Chapter of Compound Semiconductor Materials Global Technical Committee
C: Masayoshi Obara – Shin-Etsu Handotai

Japan Chapter of Environmental Health & Safety Global Technical Committee
C: Supika Mashiro – TEL
C: Hidetoshi Sakura – NuFlare Technology
C: Moray Crawford – Hatsuta Seisakusho

Japan Chapter of Facilities Global Technical Committee
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

Japan Chapter of Gases Global Technical Committee
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

Japan Chapter of Photovoltaic Global Technical Committee
C: Kazuhiro Kashima – Consultant
C: Masaaki Yamamichi – RTS Corporation

Japan Chapter of PV Materials Global Technical Committee
C: Takashi Ishihara – Mitsubishi Electric
C: Kazuhiro Kashima – Consultant
C: Tetsuo Fukuda – Nihon University

Japan Chapter of Physical Interfaces & Carriers Global Technical Committee
C: Tsuyoshi Nagashima – Miraiai
C: Kenji Yamagata – DAIFUKU
C: Noriyoshi Toyoda – Hirata Corporation

Japan Chapter of Liquid Chemicals Global Technical Committee
C: Hiroshi Tomita – Toshiba Memory
C: Hiroyuki Araki – SCREEN Semiconductor Solutions

Japan Chapter of Metrology Global Technical Committee
C: Ryoichi Watanabe – Japan Display
C: Akira Kawaguchi – Otsuka Electronics

Japan Chapter of Metrics Global Technical Committee
C: Mitsuaki Sakamoto – ZAMA Consulting

Japan Chapter of Environmental Health & Safety Global Technical Committee
C: Supika Mashiro – TEL
C: Hidetoshi Sakura – NuFlare Technology
C: Moray Crawford – Hatsuta Seisakusho
## SEMI North America (NA) RSC Organization – NA Locale

### Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

**Vice-Chair: Brian Rubow – Cimetrix**

| NA Chapter of 3D Packaging & Integration Global Technical Committee |
| C: Sesh Ramaswami – Applied Materials  
C: Chris Moore – Covalent Metrology  
C: Bill Kerr – Evergreen Enhancement |

| NA Chapter of Gases Global Technical Committee |
| C: Mohamed Saleem – Brooks Instrument |

| NA Chapter of Automated Test Equipment Global Technical Committee |
| C: Mark Roos – Roos Instruments  
C: Stacey Ajouri – Texas Instruments |

| NA Chapter of HB-LED Global Technical Committee |
| C: Mike Feng – Silian  
C: Chris Moore – Covalent Metrology  
C: Andrew Kim – InnovationforX |

| NA Chapter of Compound Semiconductor Materials Global Technical Committee |
| C: Russ Kremer – Freiberger Compound Materials  
C: James Oliver – Northrop Grumman |

| NA Chapter of Information & Control Global Technical Committee |
| C: Jack Ghiselli – Ghiselli Consulting  
C: Brian Rubow – Cimetrix  
C: James Moyne – AMAT/University of Michigan |

| NA Chapter of Environmental, Health & Safety Global Technical Committee |
| C: Chris Evanston – Salus Engineering  
C: Sean Larsen – Lam Research  
C: Bert Planting – ASML |

| NA Chapter of Liquid Chemicals Global Technical Committee |
| C: Don Hadder – Intel  
C: Steve Rogers – KMG Chemicals  
C: Laura Ledenbach – PeroxyChem  
C: Koh Murali – Mega Fluid Systems |

| NA Chapter of Facilities Global Technical Committee |
| C: Steve Lewis – BW Design Group |

| NA Chapter of MEMS/NEMS Global Technical Committee |
| C: Steve Martell – Nordson SONOSCAN  
C: Michelle Bourke – Lam Research |

| NA Chapter of Metrics Global Technical Committee |
| C: David Bouldin – Fab Consulting  
C: Mark Frankfurth – Cymer  
C: Vladimir Kraz – BestESD |

| NA Chapter of Silicon Wafer Global Technical Committee |
| C: Dinesh Gupta – STA  
C: Noel Poduje – SMS  
VC: Mike Goldstein |

| NA Chapter of Microlithography Global Technical Committee |
| C: Bryan Barnes – NIST |

| NA Chapter of Micromachining Global Technical Committee |
| C: James Moyne – AMAT/University of Michigan |

| NA Chapter of Photovoltaics Global Technical Committee |
| C: James Moyne – AMAT/University of Michigan  
C: Hugh Gotts – Air Liquide |

| NA Chapter of PV Materials Global Technical Committee |
| C: Hugh Gotts – Air Liquide |

| NA Chapter of Physical Interfaces & Carriers Global Technical Committee |
| C: Matt Fuller – Entegris  
C: Melvin Jung – Intel |

| NA RSC Technical Architect Board |
| C: James Moyne – AMAT/University of Michigan  
C: Yaw Obeng – NIST |

| NA Chapter of Traceability Global Technical Committee |
| C: Yaw Obeng – NIST  
C: David Huntley – PDF Solutions |

| NA Chapter of Traceability Global Technical Committee |
| C: Yaw Obeng – NIST  
C: David Huntley – PDF Solutions |

| NA Chapter of Traceability Global Technical Committee |
| C: Yaw Obeng – NIST  
C: David Huntley – PDF Solutions |
SEMI North America RSC Organization
China Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimetrix

China Chapter of Compound Semiconductor Materials
Global Technical Committee
C: Jiangbo Wang – HC SEMITEK
C: Guoyou Liu – CRRC TIMES

China Chapter of Photovoltaic Global Technical Committee
C: Guangchun Zhang – CanadianSolar

China Chapter of HB-LED Global Technical Committee
C: Hongbo Zuo – AURORA
C: Jiangbo Wang – HC SEMITEK

China Chapter of PV Materials
Global Technical Committee
C: Guangchun Zhang – CanadianSolar

ISC China Member
Jiangbo Wang – HC SEMITEK
**SEMI North America RSC Organization Korea Locale**

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimetrix

<table>
<thead>
<tr>
<th>Korea Chapter of Facilities Global Technical Committee</th>
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<tr>
<td>C: Kwang Sun Kim – KUT</td>
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<td>C: Jongho Chong – Samsung Display</td>
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<td>C: Kyungjin Kang – LG Electronics</td>
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<td>C: II-Ho (William) Kim – Light Measurement Solution</td>
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<td>C: Chul Hong Ahn – SK hynix</td>
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<td>C: Gun Woo Lee – Lam Research</td>
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**ISC Korea Member**
Chul Hong Ahn – SK Hynix
# SEMI North America RSC Organization Taiwan Locale

**Co-Chairs**: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering  
**Vice-Chair**: Brian Rubow – Cimetrix

<table>
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<tr>
<th>Taiwan Chapter of 3D Packaging &amp; Integration Global Technical Committee</th>
<th>Taiwan Chapter of Environmental Health &amp; Safety Global Technical Committee</th>
<th>Taiwan Chapter of Information &amp; Control Global Technical Committee</th>
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<td>C: Scott Yu – TSMC</td>
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<tr>
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<td>C: T.C. Wu – CMS/ITRI</td>
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<td>C: Jen-Chieh Wang – CMS/ITRI</td>
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<td>C: Gwo-Sheng Peng – ITRI/CMS</td>
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**ISC Taiwan Member**  
Jen-Chieh Wang – CMS/ITR
Organization of Each TC Chapter

TF = Task Force | WG = Working Group
3D Packaging & Integration (3DP&I) Global Technical Committee

**Steering Group**
- L: Masahiro Tsuriya – iNEMI
- L: Haruo Shimamoto – AIST

**Japan TC Chapter of 3D Packaging & Integration Global Technical Committee**
- C: Masahiro Tsuriya – iNEMI
- C: Haruo Shimamoto – AIST
- C: Kazunori Kato – AiT

**Thin Chip Handling TF**
- L: Haruo Shimamoto – AIST

**3D Packaging & Integration 5-Year Review TF**
- L: Masahiro Tsuriya – iNEMI
- L: Kazunori Kato – AiT

**3DS IC Bonded Layer Inspection Metrology TF**
- L: Haruo Shimamoto – AIST
- L: Shigeru Ohno – Hitachi Power Solutions

**JA 450 mm ATDP TF**
- L: Kenichi Watanabe – Lintec
- L: Sumio Masuchi – Disco

**Panel Level Packaging (PLP) Glass Carrier TF**
- L: Mark Takahashi – Namics Corp.

**Encapsulation Characteristics for Wafer Level Packaging & Panel Level Packaging TF**
- L: Masahiro Tsuriya – iNEMI
- L: Hidetoshi Arai – Apic-Yamada

**3D Packaging & Integration Bonded Wafer Stacks TF**
- L: Richard Allen – NIST
- L: Steve Martell – Nordson SONOSCAN

**3D Packaging & Integration Inspection and Metrology TF**
- L: Ilona Schmidt – Corning Inc.

**3D Packaging & Integration 5-Year Review TF**
- L: Richard Allen – NIST
- L: Kazunori Kato – AiT

**Encapsulation Characteristics for Wafer Level Packaging & Panel Level Packaging TF**
- L: Masahiro Tsuriya – iNEMI
- L: Hidetoshi Arai – Apic-Yamada

**Panel Level Packaging (PLP) Panel TF**
- L: Cristina Chu – Energetiq
- L: Richard Allen – NIST
- L: Tim Kryman – Rudolph Technologies

**Taiwan TC Chapter of 3D Packaging & Integration Global Technical Committee**
- C: Chien-Chung Lin – ITRI
- C: Wendy Chen – King Yuan Electronics
- C: Roger Hwang – ASE

**Testing TF**
- L: Wendy Chen – KYEC
- L: Roger Hwang – ASE
- L: Shang-Chun Chen – ITRI

**Middle End Process TF**
- L: Arthur Chen – NTUST
- L: Mike Chang – ITRI
Automation Technology (AT) Global Technical Committee

Europe TC Chapter of Automation Technology Global Technical Committee
C: Christian Hoffmann – PEER Group

Global Equipment Interface Specification (EIS) TF
L: Carsten Born – VITRONIC GmbH

PV Wafer Traceability TF
L: TBD

Japan TC Chapter of Automation Technology Global Technical Committee
C: Teruaki Ito – Mitsubishi Electric
C: Terry Asakawa – Vistaideal Consulting
C: Fumiyasu Obuchi – SIEemens
C: Yasuhiro Kaneko – YAMAHA Motor

A1 TF
L: Kazuki Nakahara – SIEMENS
L: Takeo Yamaki – Yokogawa Solution Services

Surface Mount Technology (SMT) TF
L: Jun Isaka – FUJI
L: Takahiko Imasu – JUKI
L: Atsushi Horibe – Panasonic

F-GEM TF
L: Terry Asakawa – Vistaideal Consulting

Taiwan TC Chapter of Automation Technology Global Technical Committee
C: K.C. Chou – ASE
C: Jen-Hui Tsai – ITRI/MMSRL
C: Gwo-Sheng Peng – ITRI/CMS
C: Jui-Ming Hua – MIRDC

PCBECI TF
L: Kuang-Fu Chang – ASE
L: Chi-Pin Chen – ITRI
L: Chi-Yuan Chang – Symtek

= Global Task Force
Automated Test Equipment (ATE)
Global Technical Committee

NA TC Chapter of Automated Test Equipment Global Technical Committee
C: Mark Roos – Roos Instruments
C: Stacey Ajouri – Texas Instruments
C: Laurent Bonneval – Teradyne

Rich Interactive Database (RITdb) TF
L: Mark Roos – Roos Instruments
L: Stacey Ajouri – Texas Instruments

Tester Event Messaging for Semiconductors (TEMS) TF
L: Laurent Bonneval – Teradyne
Environmental, Health & Safety (EH&S) Global Technical Committee

Japan TC Chapter of EHS Global Technical Committee
C: Supika Mashiro – TEL
C: Hidetoshi Sakura – NuFlare Technology
C: Moray Crawford – Hatsuta Seisakusho

Global Technical Committee

Taiwan TC Chapter of EHS Global Technical Committee
C: Shuh-Woei Yu – SAHTECH

S18 Revision TF
L: Supika Mashiro – TEL

Global S23 Revision TF
L: George Hoshi – TEL

Global Seismic Protection TF
L: Supika Mashiro – TEL

STEP Planning WG
L: Kenji Sugihara – Panasonic

Equipment Safety TF
L: Colin Shen – Mxic
L: C.C. Huang – SAHTECH
L: Wells Lin – AUO
L: Jean Yang – Innolux

Seismic TF
L: Juin-Fu Chai – NCREE

= Global Task Force
Environmental, Health & Safety (EH&S)  
Global Technical Committee

NA TC Chapter of EHS  
Global Technical Committee  
C: Chris Evanston – Salus Engineering  
C: Sean Larsen – Lam Research  
C: Bert Planting – ASML

Manufacturing Equipment Safety Subcommittee  
C: Cliff Greenberg – Safety Maven  
C: Tara Collins – ASM  
C: Lucian Girlea – Nikon Precision

Control of Hazardous Energy (CoHE) TF  
L: Andrew Giles – ESTEC  
L: Sean Larsen – Lam Research  
L: Mark Fessler – ASM

S2 Ladder & Steps TF  
L: Ron Macklin – Macklin & Associates  
L: Lindy Austin – Salus Engineering

S2 Interlock Reliability TF  
L: Bert Planting – ASML  
L: Tom Pilz – Pilz GmbH

S2 Chemical Exposure TF  
L: John Visty – Salus Engineering

S2 Non-Ionizing Radiation TF  
L: Sean Larsen – Lam Research  
L: John Visty – Salus Engineering

S2 Korean High Pressure Gas Safety TF  
L: Chris Evanston – Salus Engineering  
L: Sean Larsen – LAM Research

S2 Mechanical Design TF  
L: Ed Karl – Applied Materials

S6 Revision TF  
L: John Visty – Salus Engineering  
L: Glenn Holbrook – ASM

S10 Revision TF  
L: Eric Sklar – Safety Guru  
L: Mark Fessler – ASM  
L: Bert Planting – ASML

S22 Revision TF  
L: Chris Evanston – Salus Engineering  
L: Sean Larsen – Lam Research

S23 Revision Global TF  
L: Lauren Crane – Tokyo Electron

S22 Revision TF  
L: Chris Evanston – Salus Engineering  
L: Sean Larsen – Lam Research

Lifting Equipment TF  
L: Ron Macklin – Macklin & Associates

Fire Protection TF  
L: Eric Sklar – Safety Guru  
L: Matt Wyman – Koetter Fire

S23 Revision Global TF  
L: Lauren Crane – Tokyo Electron

S3 Revision TF  
L: Eric Sklar – Safety Guru  
L: Glenn Holbrook – ASM  
L: Andrew Petraszak – Tokyo Electron

S3 Revision TF  
L: Eric Sklar – Safety Guru  
L: Glenn Holbrook – ASM  
L: Andrew Petraszak – Tokyo Electron

Energetic Materials EHS TF  
L: Eric Sklar – Safety Guru

Global Seismic Protection TF  
L: Lauren Crane – Tokyo Electron

Ergonomics TF  
L: Ron Macklin – Macklin & Associates  
L: Paul Schwab – Texas Instruments

S2 Mechanical Design TF  
L: Ed Karl – Applied Materials

S22 Revision TF  
L: Chris Evanston – Salus Engineering  
L: Sean Larsen – Lam Research

Lifting Equipment TF  
L: Ron Macklin – Macklin & Associates

S2 Ladder & Steps TF  
L: Ron Macklin – Macklin & Associates  
L: Lindy Austin – Salus Engineering

S2 Chemical Exposure TF  
L: John Visty – Salus Engineering

S2 Non-Ionizing Radiation TF  
L: Sean Larsen – Lam Research  
L: John Visty – Salus Engineering

S2 Korean High Pressure Gas Safety TF  
L: Chris Evanston – Salus Engineering  
L: Sean Larsen – LAM Research

S2 Mechanical Design TF  
L: Ed Karl – Applied Materials
FPD Metrology
Global Technical Committee

Japan TC Chapter of FPD Metrology
Global Technical Committee
C: Ryoichi Watanabe – Japan Display
C: Akira Kawaguchi – Otsuka Electronics

Korea TC Chapter of FPD Metrology
Global Technical Committee
C: Jongho Chong – Samsung Display
C: Kyungjin Kang – LG Electronics

Taiwan TC Chapter of FPD Metrology
Global Technical Committee
C: Jia-Ming Liu – TDMDA
C: Jen-Chieh Wang – CMS/ITRI

Perceptual Viewing Angle TF
L: Myongyoung Lee – LG Electronics

Perceptual Image Quality TF
L: Jongho Chong – Samsung Display

Flexible Display TF
L: Chao-Hua Wen – ITRI

Transparent Display TF
L: Pei-Li Sun – NTUST
L: Justic Lin – Acer
HB-LED Global Technical Committee

NA TC Chapter of HB-LED Global Technical Committee
C: Mike Feng – Silian
C: Chris Moore – Covalent Metrology
C: Andrew Kim – InnovationforX

China TC Chapter of HB-LED Global Technical Committee
C: Hongbo Zuo – AURORA
C: Jiangbo Wang – HC SEMITEK

Patterned Sapphire Substrate (PSS) TF
L: Open

HB-LED Wafer TF
L: Open

HB-LED Equipment Communication Interfaces TF (Inactive)
L: Brian Rubow – Cimetrix

HB-LED Impurities & Defects in Sapphire Wafers TF (Inactive)
L: Luke Glinski – GT Advanced Technologies

HB-LED Source Materials TF
L: Mayank Bulsara – Matheson

Test Methods TF (Inactive)
L: Peter Wagner – Self

Single Crystal Sapphire TF
L: Yong Ji – GHTOT
L: Xinhong Yang – AURORA

Sapphire Single Crystal Ingot TF
L: Hongbo Zuo – AURORA

GaN based LED Epitaxial Wafer TF
L: Jiangbo Wang – HC SEMITEK

Sapphire Single Crystal Orientation TF (Inactive)
L: Songbin Zhao – DDXDF

Patterned Sapphire Substrate TF
L: Jianzhe Liu – BST

HB-LED Equipment Communication Interface TF
L: Steven Lee – AMEC
L: Clare Liu – Cimetrix

HB-LED Equipment Automation Interfaces TF (Inactive)
L: Daniel Babbs – Brooks Automation
L: Jeff Felipe – Entegris

HB-LED Equipment Impurities & Defects in Sapphire Wafers TF (Inactive)
L: Luke Glinski – GT Advanced Technologies

HB-LED Source Materials TF
L: Mayank Bulsara – Matheson

Test Methods TF (Inactive)
L: Peter Wagner – Self

Standards

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Information & Control (I&C) Global Technical Communities

NA TC Chapter of Information & Control Global Technical Committee
C: Brian Rubow – Cimetrix
C: Jack Ghiselli – Ghiselli Consulting
C: James Moyne – AMAT/University of Michigan

Taiwan TC Chapter of Information & Control Global Technical Committee
C: Scott Yu – TSMC

Graphical User Interfaces (GUI) TF
L: Frank H. Summers – Industrial-Strength Graphics International
L: Tami Tracey – Cimetrix

Diagnostic Data Acquisition (DDA) TF
L: Brian Rubow – Cimetrix
L: Albert Fuchigami – PEER Group

Energy Saving Equipment Communication (ESEC) TF
L: Mike Czerniak – Edwards Vacuum
L: Andreas Neuber – Applied Materials

GEM300 TF
L: Brian Rubow – Cimetrix
L: Chris Maloney – Intel

Sensor Bus TF
L: James Moyne – AMAT/University of Michigan

Process Control System NA (PCS) TF
L: James Moyne – AMAT/University of Michigan
L: Chris Maloney – Intel

Fab & Equipment Computer and Device Security (CDS) TF
L: Ryan Bond – Intel
L: Richard Howard – Cimetrix

Advanced Backend Factory Integration (ABFI) TF
L: Dave Huntley – PDF Solutions
L: Brian Rubow – Cimetrix
L: Luis Lim – Miracom

GEM300 TF
L: Robin Liao – TSMC

Backend Factory Integration TF
L: Ivan Chen – TSMC

Equipment Information Integration TF
L: Robin Liao – TSMC

Fab & Equipment Information Security TF
L: Leon Chang – TSMC
L: Ares Cho – ITRI
Liquid Chemicals
Global Technical Committee

Europe TC Chapter of Liquid Chemicals Global Technical Committee
C: Jochen Ruth – Pall Corporation

Precursor Specifications TF
L: Paul Williams – SAFC Hitech

Solvents in Advanced Processes TF
L: TBD

Japan TC Chapter of Liquid Chemicals Global Technical Committee
C: Hiroshi Tomita – KIOXIA
C: Hiroyuki Araki – SCREEN Semiconductor Solutions

Liquid Filter TF
L: Takuya Nagafuchi – Nihon Entegris
L: Tomoyuki Takakura – Pall

Diaphragm Valve TF
L: Shigeru Ohsugi – CKD
L: Kimihito Sasao – Advance Electric

Trace Metal Analysis for High Pure IPA TF
L: Takuya Nagafuchi – Nihon Entegris
L: Hiroshi Sugawara – Organo

Liquid-Borne Particle Counter TF
L: Kaoru Kondo – RION
L: Kazutoshi Kato – PMS Division/Spectris Co., Ltd.

Welding Fitting TF
L: Kimihito Sasao – Advance Electric
L: Takashi Hasegawa – KITZ SCT

Ultra Pure Liquid Evaluation Study Group
L: Kaoru Kondo – RION
L: Hiroshi Sugawara – ORGANO

NA TC Chapter of Liquid Chemicals Global Technical Committee
C: Don Hadder – Intel
C: Steve Rogers – KMG Chemicals
C: Laura Ledenbach – PeroxyChem
C: Koh Murai – Mega Fluid Systems

Chemical Analytical Methods (CAM) TF
L: Don Hadder – Intel
L: David Kandiyeli – Mega Fluid Systems

High Purity Liquid Assemblies & Systems TF (Inactive)
L: Koh Murai – Mega Fluid Systems
L: David Kandiyeli – Mega Fluid Systems

High Purity Polymer Materials & Components TF
L: Bob McIntosh – GF Piping

Ultra Pure Water (UPW) TF
L: Slava Libman – FTD Solutions
L: Bob McIntosh – GF Piping
MEMS/NEMS
Global Technical Committee

NA TC Chapter of MEMS/NEMS Global Technical Committee
C: Steve Martell – Nordson SONOSCAN
C: Michelle Bourke – Lam Research

MEMS Packaging TF (Inactive)
L: Steve Martell – Nordson SONOSCAN

Wafer Bond TF (Inactive)
L: Richard Allen – NIST

MEMS Reliability TF
L: Allyson Hartzell – Veryst

MEMS Microfluidics TF
L: Mark Tondra – Diagnostic Biosensors

International MEMS Terminology TF (Inactive)
L: Steve Martell – Nordson SONOSCAN

MEMS Material Characterization TF
L: Richard Allen – NIST

MEMS Substrate TF
L: Chris Moore – Covalent Metrology
Metrics
Global Technical Committee

Europe TC Chapter of Metrics
Global Technical Committee
C: Open

Japan TC Chapter of Metrics
Global Technical Committee
C: Mitsune Sakamoto – ZAMA Consulting

Japan RF Measurement Liaison TF
L: Supika Mashiro – TEL

ESD/ESC TF
L: TBD

Int’l Environmental Contamination Control TF
L: Mikio Furukawa – Shin-Etsu Polymer

NA TC Chapter of Metrics
Global Technical Committee
C: David Bouldin – Fab Consulting
C: Mark Frankfurth – Cymer
C: Vladimir Kraz – BestESD
TE: Carolyn Busing – Self
TA: Greg Francis – Cymer

Equipment RAMP Metrics TF
L: David Busing – Consultant
L: Steven Meyer – Intel
L: Russell Fitzpatrick – Applied Materials

Equipment Cost of Ownership (ECOO) TF
L: David Jimenez – WWK
L: David Bouldin – Fab Consulting

EMC TF
L: Vladimir Kraz – BestESD
L: Mark Frankfurth – Cymer

RF Measurements TF
L: Supika Mashiro – TEL

ESD/ESC TF
L: Chuck McClain – NorthWest Electrostatic Services
L: Russell Fitzpatrick – Applied Materials

Critical Chamber Components (CCC) Test Methods TF
L: Michael Cox – Intel
L: Supika Mashiro – TEL

= Global Task Force
Micropatterning
Global Technical Committee

NA TC Chapter of Microlithography
Global Technical Committee
C: Bryan Barnes – NIST

Patterning Metrology TF
L: Bryan Barnes – NIST

Mask Orders TF
L: Wes Erck – Oasis Tooling

P47 Revision TF
L: Chris Mack – Fractilia
L: Gian Lorusso – IMEC
L: Atsuko Yamaguchi – Hitachi Ltd.
PV Materials
Global Technical Committee

Europe TC Chapter of PV Materials
Global Technical Committee
C: Peter Wagner – Consultant
C: Christian Hagendorf – FhG-CSP

Japan TC Chapter of PV Materials
Global Technical Committee
C: Takashi Ishihara – Mitsubishi Electric
C: Kazuhiko Kashima – Consultant
C: Tetsuo Fukuda – Nihon University

NA TC Chapter of PV Materials
Global Technical Committee
C: Hugh Gotts – Air Liquide Electronics US

China TC Chapter of PV Materials
Global Technical Committee
C: Guangchun Zhang – Canadian Solar

Int’l PV Analytical Test Methods,
Metrology, and Inspection TF
L: TBD

Japan PV Materials TF
L: Tetsuo Fukuda – Nihon University
L: Takashi Ishihara – Mitsubishi Electric

PV Silicon Materials TF
L: Peter Wagner – Consultant

PV Material Degradation TF
L: Max Koentopp – Hanwha Q-cells
L: Christian Hagendorf – FhG-CSP

Int’l PV Analytical Test Methods,
Metrology, and Inspection TF
L: Hugh Gotts – Air Liquide Electronics US
L: Chris Moore – Covalent Metrology

PV Silicon Raw Materials TF
L: Wenfeng Lu – GCL
L: Dongxu Chu – SINOSICO
L: Li He – CPVT

PV Silicon Wafer TF
L: Yuepeng Wan – GCL
L: Rui Zhou – LONGi
L: Dongli Hu – GCL

= Global Task Force
Physical Interfaces & Carriers (PI&C) Global Technical Committee

Europe TC Chapter of Physical Interfaces & Carriers Global Technical Committee
C: Frank Petzold – Trustsec

International Reticle SMIF Pod & Loadport Interoperability TF
L: Jan Rothe – GLOBALFOUNDRIES

Panel Level Packaging (PLP) Panel FOUP TF
L: Shoji Komatsu – Acteon NEXT
L: John Rudolph – Intel

Japan TC Chapter of Physical Interfaces & Carriers Global Technical Committee
C: Tsuyoshi Nagashima – Miraial
C: Kenji Yamagata – DAIFUKU
C: Noriyoshi Toyoda – Hirata Corporation
TA: Shoji Komatsu – Acteon NEXT

Japan Electron Microscopy Workflow Liaison TF
L: Kyochiro Asayama – JEOL
L: Tsuyoshi Onishi – Hitachi High-Technologies

Global PIC Maintenance TF
L: Shoji Komatsu – Acteon NEXT

300 mm Tape Frame PI&C TF
L: Hayato Iwamoto – Sony Semiconductor Solutions
L: Hisashi Goto – Sony Semiconductor Solutions
L: Naomune Taniguchi – Tokyo Seimitsu

NA TC Chapter of Physical Interfaces & Carriers Global Technical Committee
C: Matt Fuller – Entegris
C: Melvin Jung – Intel

International Reticle SMIF Pod & Loadport Interoperability TF (Inactive)
L: Jan Rothe – GLOBALFOUNDRIES

Global PIC Maintenance TF
L: Larry Hartsough – UA Associates

Electron Microscopy Workflow TF
L: Laurens Kwakman – Thermo Fisher Scientific

= Global Task Force
Silicon Wafer
Global Technical Committee

Europe TC Chapter of Silicon Wafer
Global Technical Committee
C: Werner Bergholz – Jacobs University of
Bremen
C: Peter Wagner – Consultant
C: Fritz Passek – Siltronic

International Advanced Surface
Inspection TF
L: Frank Riedel – Siltronic

International Terminology TF
L: Peter Wagner – Consultant

International Polished Wafers TF
L: Frank Riedel – Siltronic

International Advanced Wafer
Geometry TF
L: Fritz Passek – Siltronic
L: Frank Riedel – Siltronic

International Test Methods TF
L: Peter Wagner – Consultant

NA TC Chapter of Silicon Wafer
Global Technical Committee
C: Dinesh Gupta – STA
C: Noel Poduje – SMS

International Annealed Wafers
TF
L: Dinesh Gupta – STA

International Epitaxial Wafers
TF
L: Dinesh Gupta – STA

International Polished Wafers
TF
L: TBD

International Terminology TF
L: TBD

International Test Methods TF
L: Dinesh Gupta – STA

International Advanced Wafer
Geometry TF
L: Noel Poduje – SMS
L: Frank Riedel – Siltronic

International SOI Wafers TF
L: Gerd Pfeiffer – GLOBALFOUNDRIES

International Automated
Advance Surface Inspection TF
L: Kurt Haller – KLA-Tencor

= Global Task Force
Silicon Wafer
Global Technical Committee

International Terminology TF
L: Tetsuya Nakai – SUMCO

International SOI Wafers TF
L: Atsushi Ogura – Meiji University
L: Tetsuya Nakai – SUMCO

International Polished Wafers TF
L: Yasutoshi Takamoti – GlobalWafers Japan

International Annealed Wafers TF
L: Koji Araki – GlobalWafers Japan

International Epitaxial Wafers TF
L: Naohisa Toda – Shin-Etsu Handotai

Japan TC Chapter of Silicon Wafer
Global Technical Committee
C: Naoyuki Kawai – Meiji University
C: Tetsuya Nakai – SUMCO

International Test Method TF
L: Ryuji Takeda – GlobalWafers Japan

Japan Test Method TF
L: Ryuji Takeda – GlobalWafers Japan
L: Tsuyoshi Otsuki – Shin-Etsu Handotai
L: Mikako Omata – SCAS

Surface Metal Chemical Analysis WG
L: Ryuji Takeda – GlobalWafers Japan
L: Ryo Machida – SCAS

GOI WG
L: Tsuyoshi Otsuki – Shin-Etsu Handotai

Surface Organic Contaminant Analysis WG
L: Mikako Omata – SCAS

Bulk Heavy Metal Analysis by Electrical Measurement WG
L: Shingo Sumie – KOBELCO
L: Masaru Akamatsu – KOBELCO

BMD DZ WG
L: Ryuji Takeda – GlobalWafers Japan

JA Shipping Box TF
L: Shoji Komatsu – Acteon NEXT
L: Tsuyoshi Nagashima – Miraial

International 450 mm Shipping Box TF
L: Shoji Komatsu – Acteon NEXT

Japan JWG TF
L: Masanori Yoshise – Wafer Information Service

International Advanced Surface Inspection TF
L: Masami Ikota – Hitachi-High Technologies

= Global Task Force

Standards
Traceability
Global Technical Committee

Japan TC Chapter of Traceability
Global Technical Committee
C: Yoichi Iga – JEITA
C: Hirokazu Tsunobuchi – Keyence

- 5-Year Review TF
  L: Hirokazu Tsunobuchi – Keyence

- Japan Equipment & Materials
  Traceability Liaison TF
  L: Yoichi Iga – JEITA
  L: Hirokazu Tsunobuchi – Keyence

- Japan Single Device
  Traceability Liaison TF
  L: Yoichi Iga – JEITA
  L: Hirokazu Tsunobuchi – Keyence

NA TC Chapter of Traceability
Global Technical Committee
C: Yaw Obeng – NIST
C: David Huntley – PDF Solutions

- 5-Year Review TF
  L: Masanori Yoshise – Self

- Equipment and Materials
  Traceability TF
  L: Eric Bruce – Samsung
  L: Lance Dyrdahl – Lam Research
  L: Jeff Hanan – GlobalFoundries

- Single Device Traceability TF
  L: Dave Huntley – PDF Solutions
  L: Chris Portelli – STMicro
  L: Zoe Conroy – Cisco